

T-3018
Component Lead Tinning Flux

Product Description

Hasaconi T-3018 Component Lead Tinning Flux is a low solid content flux formulated with high purity specialty chemicals for improved activity and surface tension reduction capacities. This flux is halide-free, alcohol-based flux designed for dipping applications on component leads made of nickel-iron (Alloy 42), nickel, and copper. The residue can be easily removed with hot deionised water or soft water at 40 - 50 °C.

Application

T-3018 is specially formulated for dipping application. A uniform coat of flux is required for consistent and optimum solderability. This flux is compatible with both SnPb and lead free solders.

Residue Removal

The residue left after soldering is hygroscopic and ionisable. Complete residue removal immediately after soldering is recommended. Removal of the residue can best be achieved with water at a minimum temperature of 40°C, followed by a final deionised water rinse.

Recommended Solvent

No solvent is required.

Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

Storage

Under proper storage condition, T-3018 can be stored for about 6 months.

Packaging

Available in 20kg/carboy.

Specification

Item	Result
State	Liquid
Colour	Slightly Yellowish
Specific Gravity @ 22°C	0.879 +/- 0.005
<small>JIS Z 3197 8.2.2</small>	
Non-volatile Solid Content (110°C, 3hr)	10.6 +/- 0.5 wt%
<small>IPC-TM-650 2.3.34</small>	
<small>JIS Z 3197 8.1.3</small>	
Halide Content	Not added
<small>JIS Z 3197 8.1.4.2.1</small>	
Water Extract Resistivity	> 1 x 10 ⁴ Ω-cm
<small>JIS Z 3197 8.1.1</small>	
Acid Value Test	128 +/- 5 mg KOH/g flux
<small>IPC-TM-650 2.3.13</small>	
<small>JIS Z 3197 8.1.4.1</small>	
Copper Corrosion Test	Pass
<small>IPC-TM-650 2.6.15</small>	
<small>JIS Z 3197 8.4.1</small>	
pH	4.2
Spread Factor	> 80% (Brass Plating)
<small>JIS Z 3197 8.3.1.1</small>	> 80% (Copper Plating)
Surface Finish	Slightly Matte

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